CLAIMS

1. A fiber board manufactured by bonding kenaf fibers obtained by fiber-opening kenaf with a thermosetting adhesive agent,

wherein the kenaf fibers having an average length of 10 to 200 mm with an average diameter being set in a range of 10 to 300 μm are used, and a fiber mat formed by aggregating the kenaf fibers is impregnated with the thermosetting adhesive agent so that the fiber board is formed so as to have a density of 600 to 900 kg/m^3.

2. The fiber board according to claim 1, wherein the thermosetting adhesive agent is a phenolic resin having an average molecular weight of 400 to 700, which contains 10 to 40% by weight of a monomer and 60 to 90% by weight of a polymer having a molecular weight of 200 to 2,000.

3. The fiber board according to claim 1, wherein the pH of the thermosetting adhesive agent is set to not more than 10.

4. The fiber board according to claim 1, wherein the kenaf fibers have a standard deviation in length of not more than 20 mm and a standard deviation in diameter of not more than 50 μm.

5. A fiber board, comprising:

kenaf fibers having an average length of 10 to 200 mm and an average diameter of 10 to 300 μm, and

a thermosetting adhesive agent,

the fiber board having a density of 600 to 900 kg/m^3.

6. The fiber board according to claim 5, wherein the fibers have a standard deviation in length of not more than 20 mm and a standard deviation in diameter of not more than 50 μm.

7. The fiber board according to claim 5, wherein the thermosetting adhesive agent is a phenolic resin having an average molecular weight of 400 to 700, which contains 10 to 40% by weight of a monomer and 60 to 90% by weight of a polymer having a molecular weight of 200 to 2,000.

8. The fiber board according to claim 5, wherein a moisture permeation resistance of the board is 5,400 ($m^2 \cdot s \cdot Pa$)/ng or less in accordance with JIS A 5905 (moisture permeability measuring method for construction materials).

9. The fiber board according to claim 5, wherein a bending strength is at least 44 MPa in accordance with JIS A 5905 (fiber board).

10. The fiber board according to claim 5, wherein a peel strength is at least 0.5 MPa in accordance with JIS A 5905 (fiber board).